

40V N-Channel Power MOSFET

• General Description

It combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

• Features

- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

• Application

- BLDC Motor driver
- DC-DC
- Battery protection

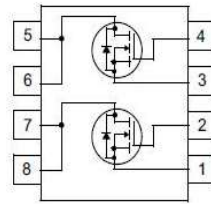
• Ordering Information:

Part NO.	ZMD68404N
Marking	ZMD68404
Packing Information	REEL TAPE
Basic ordering unit (pcs)	3000

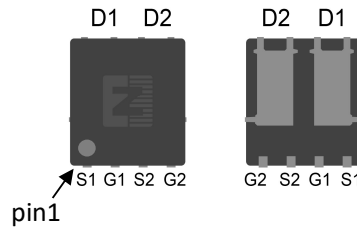
• Absolute Maximum Ratings ($T_C=25^\circ\text{C}$)

Parameter	Symbol	Conditions	Value	Unit
Drain-Source Voltage	V_{DS}		40	V
Gate-Source Voltage	V_{GS}		± 20	V
Continuous Drain Current	I_D	$T_C=25^\circ\text{C}$	47	A
	I_D	$T_C=75^\circ\text{C}$	38	A
	I_D	$T_C=100^\circ\text{C}$	31	A
Pulsed Drain Current	I_{DM}	Pulsed; $t_p \leq 10 \mu\text{s}$; $T_{mb} = 25^\circ\text{C}$;	188	A
Total Power Dissipation	P_D	$T_C=25^\circ\text{C}$	35	W
Total Power Dissipation	P_D	$T_A=25^\circ\text{C}$	2.5	W
Operating Junction Temperature	T_J		-55 to +150	$^\circ\text{C}$
Storage Temperature	T_{STG}		-55 to +150	$^\circ\text{C}$
Single Pulse Avalanche Energy	E_{AS}	$L=0.1\text{mH}$, $V_{GS}=10\text{V}$, $R_g=25\Omega$,	100	mJ
		$L=0.5\text{mH}$, $V_{GS}=10\text{V}$, $R_g=25\Omega$,	190	mJ
ESD Level (HBM)	CLASS 2			

• Product Summary



$V_{DS} = 40\text{V}$
 $R_{DS(ON)} = 6\text{m}\Omega$
 $I_D = 47\text{A}$



DFN5*6



•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}		-	3.6	$^{\circ}C/W$
Thermal resistance, junction-ambient ^①	R_{thJA}		-	50	$^{\circ}C/W$
Soldering temperature	T_{sold}		-	260	$^{\circ}C$

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	40			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1.3	1.8	2.5	V
Drain-Source Leakage Current	I_{DSS}	$V_{GS}=0V, V_{DS}=40V$			1.0	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$			100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=18A$		6	9	m Ω
		$V_{GS}=4.5V, I_D=16A$		8	12	m Ω
Forward Transconductance	g_{FS}	$V_{DS}=5V, I_{SD}=10A$		8		S
Diode Forward Voltage	V_{FSD}	$V_{GS}=0V, I_{SD}=18A$			1.3	V

•Dynamic characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Input capacitance	C_{iss}	$f=1MHz, V_{DS}=25V$	-	3300	-	pF
Output capacitance	C_{oss}		-	232	-	
Reverse transfer capacitance	C_{rss}		-	171	-	
Gate Resistance	R_g	$f=1MHz$	-	1.4		Ω
Total gate charge	Q_g	$V_{DD}=15V, I_D=20A, V_{GS}=10V$	-	51	-	nC
	$Q_g(4.5V)$		-	24	-	
Gate - Source charge	Q_{gs}		-	9	-	
Gate - Drain charge	Q_{gd}		-	9.6	-	
Turn-ON Delay time	$t_{D(on)}$		$V_{GS}=10V, V_{DS}=15V, R_G=3.3\Omega, I_D=20A$	-	10	
Turn-ON Rise time	t_r	-		55	-	ns
Turn-Off Delay time	$t_{D(off)}$	-		25	-	ns
Turn-Off Fall time	t_f	-		42	-	ns
Reverse Recovery Time	t_{RR}	$V_{DD}=20V, dI_S/dt=100A/\mu s, I_S=20A$	-	23	-	ns
Reverse Recovery Charge	Q_{RR}		-	19	-	nC

Fig.1 Gate-Charge Characteristics

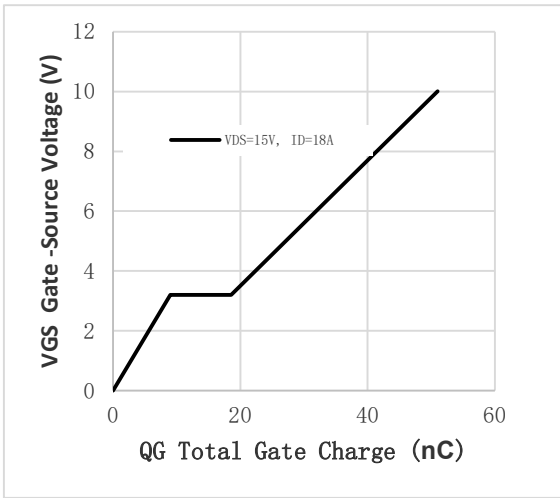


Fig.2 Capacitance Characteristics

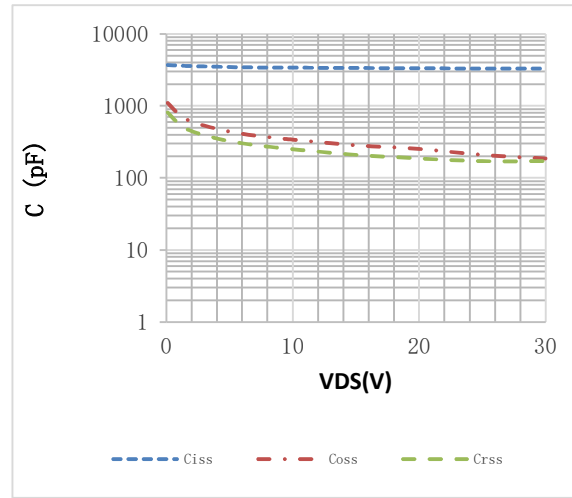


Fig.3 Power Dissipation

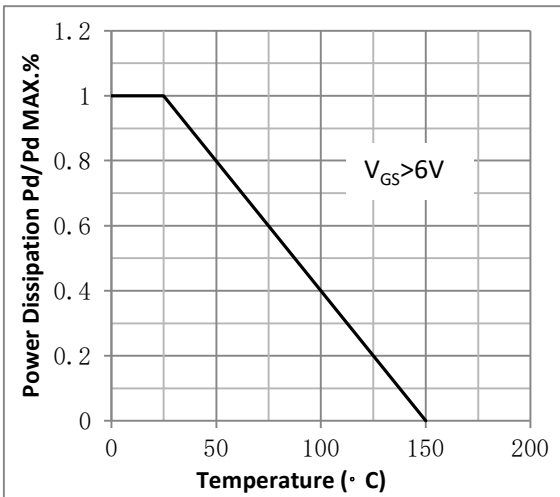


Fig.4 Typical output Characteristics

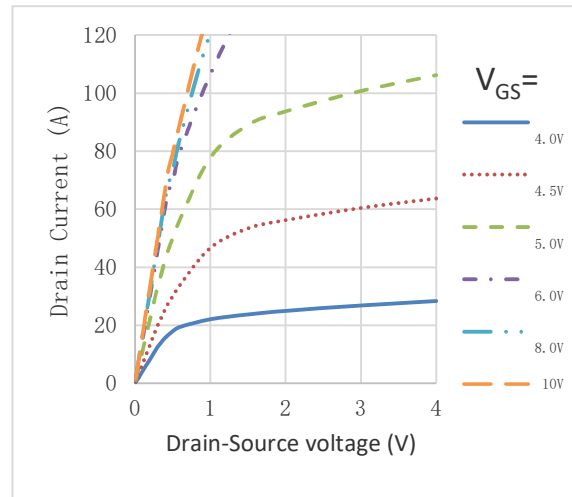


Fig.5 Threshold Voltage V.S Junction Temperature

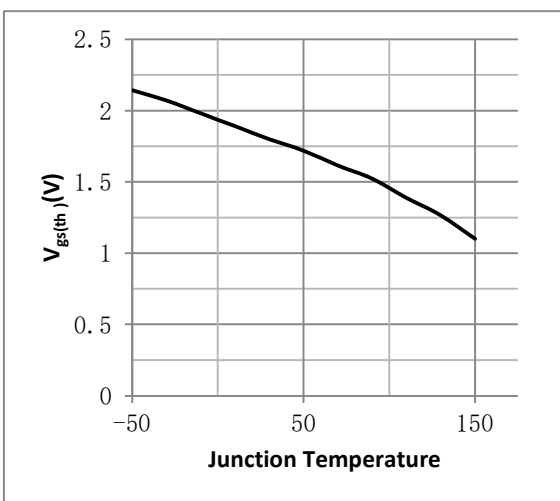


Fig.6 Resistance V.S Drain Current

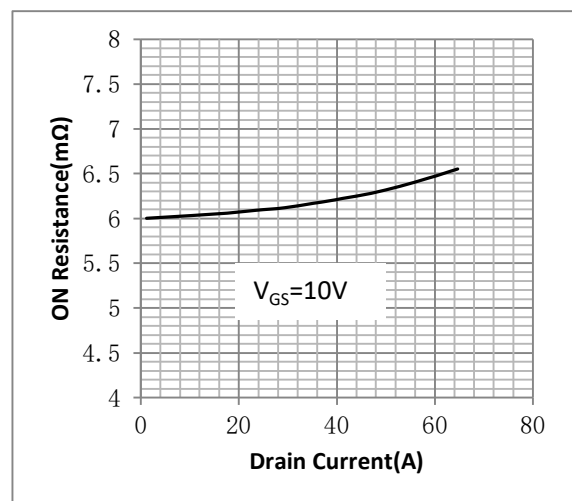


Fig.7 On-Resistance VS Gate Source Voltage

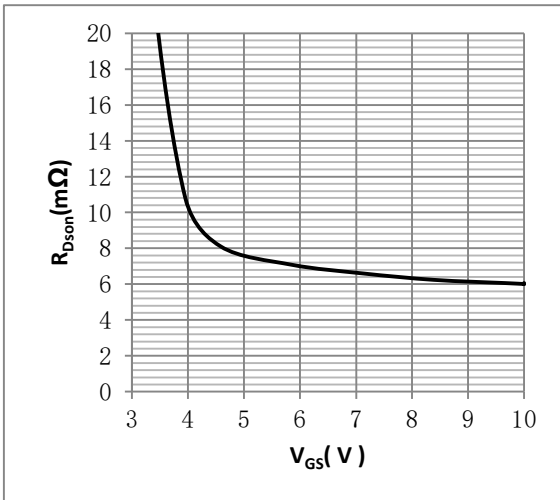


Fig.8 On-Resistance V.S Junction Temperature

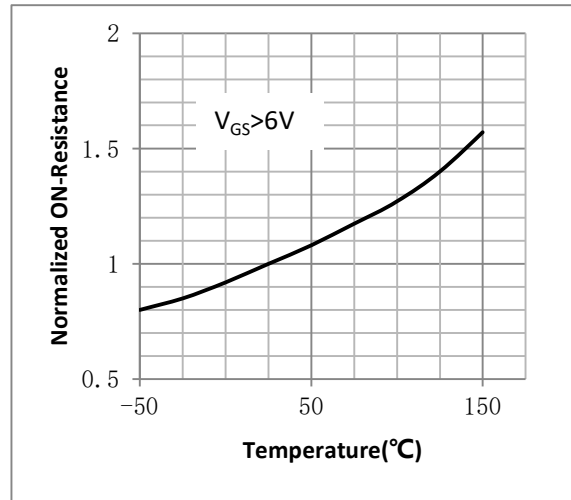


Figure 9. Diode Forward Voltage vs. Current

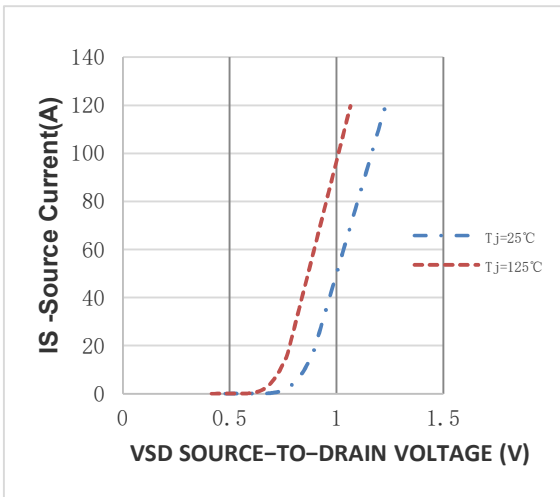


Figure 10. Transfer Characteristics

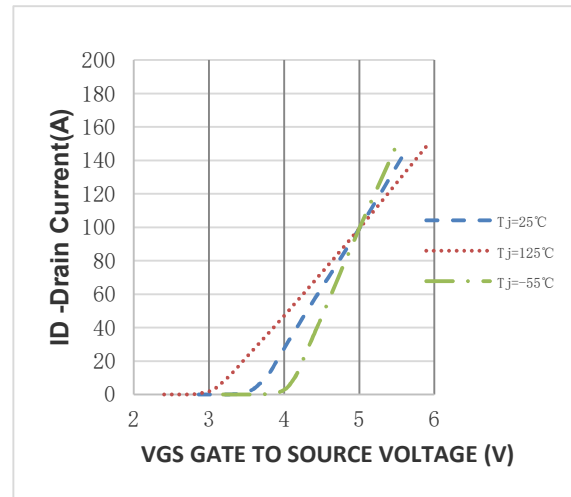


Fig.11 Safe Operating Area

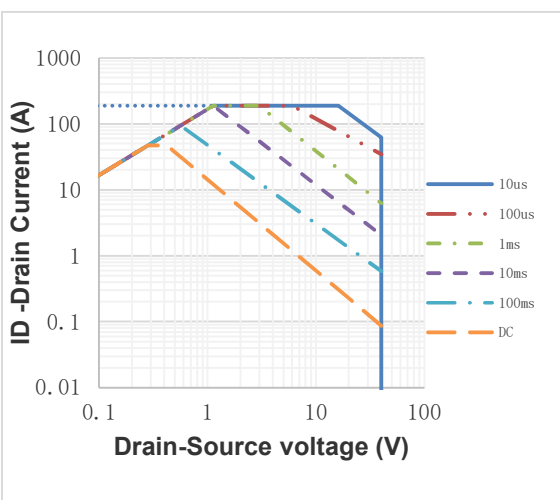
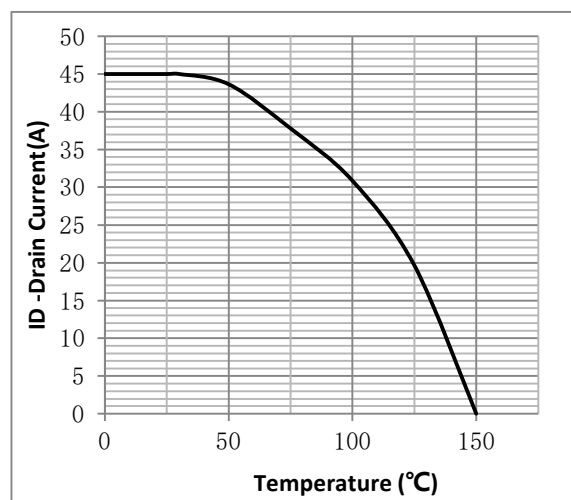
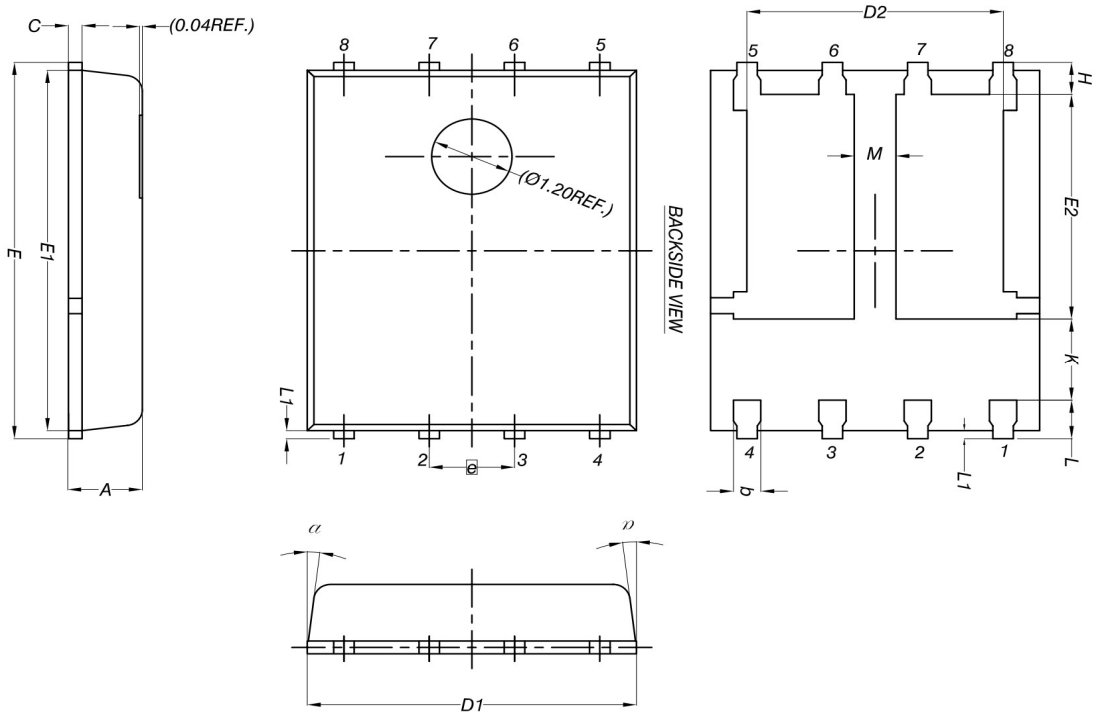


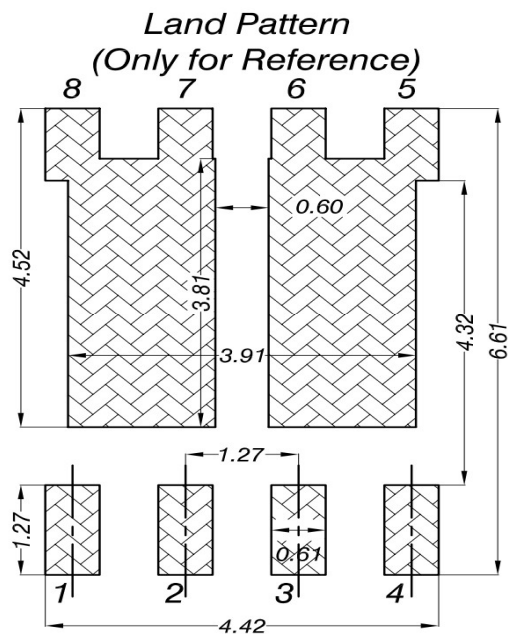
Fig.12 ID vs. Case Temperature[Ⓞ]



•DFN5*6 Package Outline



DIM.	MILLIMETERS		
	MIN.	NUM.	MAX.
A	0.90	1.00	1.15
b	0.33	0.41	0.51
c	0.19	0.25	0.29
D1	4.80	4.90	5.00
D2	3.60	3.95	4.30
E	5.90	6.00	6.10
E1	5.70	5.75	5.80
E2	3.28	3.58	3.88
e	1.27 BSC		
H	0.41	0.51	0.61
K	1.10	-	-
L	0.51	0.61	0.71
L1	0.06	0.13	0.2
M	0.50	-	-
α	0°	-	12°



Note:

- ① Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate;
- ② Practically the current will be limited by PCB, thermal design and operating temperature.
VGS=10V.

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Revision History

Version	Date	Change
A	2021.2.3	
B	2021.9.5	1.Add Reach, HF figure
C	2023.12.20	corrected.2. Correct dynamic characteristics and characteristic curves.